

Title (en)

ANGLE-ADJUSTABLE AND/OR ANGLED PRINTED CIRCUIT BOARD STRUCTURE HAVING AT LEAST TWO PRINTED CIRCUIT BOARD SECTIONS AND METHOD FOR PRODUCING SAME

Title (de)

ABWINKELBARE UND/ODER ABGEWINKELTE LEITERPLATTENSTRUKTUR MIT ZUMINDEST ZWEI LEITERPLATTENABSCHNITTEN UND VERFAHREN ZU DEREN HERSTELLUNG

Title (fr)

STRUCTURE DE CARTE DE CIRCUITS IMPRIMÉS COUDÉE ET/OU POUVANT ÊTRE COUDÉE ET COMPRENANT AU MOINS DEUX PARTIES DE CARTE DE CIRCUITS IMPRIMÉS, ET PROCÉDÉ DE FABRICATION DE LADITE STRUCTURE

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Application

EP 13794857 A 20131115

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Abstract (en)

[origin: WO2014076233A1] The invention relates to an angle-adjustable and/or angled printed circuit board structure having at least two printed circuit board sections arrangeable or arranged angularly with respect to one another, wherein the printed circuit board structure contains at least one conduction element which is embedded at least predominantly in the printed circuit board structure and which extends between two connection locations and is electrically conductively connected to said connection locations, wherein the two connection locations are situated on different printed circuit board sections, wherein the printed circuit board sections are angle-adjustable and/or angled relative to one another with maintenance of the connections between the connection locations and the at least one conduction element and with bending of the at least one conduction element via a bending edge between the printed circuit board sections. In order to improve the electrical and mechanical connection between the printed circuit board sections, the invention provides for the conduction element to have a larger extent along the bending edge than perpendicularly thereto, as viewed in cross section. A corresponding method for producing this printed circuit board structure is likewise claimed.

IPC 8 full level

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CPC (source: EP US)

H05K 1/0278 (2013.01 - EP US); **H05K 1/028** (2013.01 - US); **H05K 1/111** (2013.01 - US); **H05K 3/0014** (2013.01 - US); **H05K 3/0017** (2013.01 - US); **H05K 1/0265** (2013.01 - EP US); **H05K 3/202** (2013.01 - EP US); **H05K 2201/0275** (2013.01 - US); **H05K 2201/0355** (2013.01 - US); **H05K 2201/0376** (2013.01 - EP US); **H05K 2201/057** (2013.01 - US); **H05K 2201/09027** (2013.01 - US); **H05K 2201/0969** (2013.01 - EP US); **H05K 2201/1028** (2013.01 - EP US); **Y10T 29/49156** (2015.01 - EP US)

Citation (search report)

See references of WO 2014076233A1

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